



Laminar nanofluid flow in microheat-sinks

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Abstract

In response to the ever increasing demand for smaller and lighter high-performance cooling devices, steady laminar liquid nanofluid flow in microchannels is simulated and analyzed. Considering two types of nanofluids, i.e., copper-oxide nanospheres at low volume concentrations in water or ethylene glycol, the conjugated heat transfer problem for microheat-sinks has been numerically solved. Employing new models for the effective thermal conductivity and dynamic viscosity of nanofluids, the impact of nanoparticle concentrations in these two mixture flows on the micro-channel pressure gradients, temperature profiles and Nusselt numbers are computed, in light of aspect ratio, viscous dissipation, and enhanced temperature effects. Based on these results, the following can be recommended for microheat-sink performance improvements: Use of large high-Prandtl number carrier fluids, nanoparticles at high volume concentrations of about 4% with elevated thermal conductivities and dielectric constants very close to that of the carrier fluid, microchannels with high aspect ratios, and treated channel walls to avoid nanoparticle accumulation.

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1. Introduction

In order to cope with ever increasing demands from the electronic, automotive and aerospace industries, cooling devices have to be small in size, light-weight and of high performance. The level and reliability of heat rejection efficiency largely determine the optimal design of cooling devices. Inspired by the microchannel heat-sink idea proposed by Tuckerman and Pease [1], several new designs and modeling approaches of high performance cooling devices have been proposed,

including the fin model and the “porous medium” model. For example, Koh and Colony [2] introduced the porous medium model, which Tien and Kuo [3] expanded by adopting a modified Darcy’s law for the momentum equation and volume-averaging for the energy equation. Kim et al. [4] compared analytically the one-equation and two-equation models for heat transfer in microchannel heat sinks. They reported that the one-equation model is valid only when the fluid phase is in local thermal equilibrium with the solid phase. They investigated parameters such as the Darcy number and conductivity ratio, which influence the validity of local thermal equilibrium, and concluded that the one-equation model is adequate for channels with high aspect ratios as well as for flows of highly conductive fluids. Zhao

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